



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-08-12
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6R*1874ARY	A	BO2A	2014-08-12
Amount	UoM	Unit type	ST ECOPACK Grade	
54.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	5 - 4.4 - 0.9	14	J bend	
Comment	TSSOP 14 BODY 4.4 PITCH 0.65; MD valid for CP:TS1874AIYPT, TS1874IYPT, TSV324AIYPT, TSV324IYPT.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6R*1874ARY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.972	mg	supplier	die	Silicon (Si)	7440-21-3		2.95	mg	992598	54630
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.02	mg	6729	370
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.002	mg	673	37
Leadframe	Copper & its alloys	23.872	mg	supplier	alloy	Copper (Cu)	7440-50-8		23.82	mg	997822	441111
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.011	mg	461	204
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.02	mg	838	370
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.018	mg	754	333
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	42	19
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	42	19
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	42	19
Die attach	Other Organic Materials	0.949	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.864	mg	910432	16000
Die attach				supplier	glue or tape	acrylate	Proprietary		0.047	mg	49526	870
Die attach				supplier	glue or tape	Methacrylate	Proprietary		0.038	mg	40042	704
Bonding wire	Other inorganic materials	0.152	mg	supplier	wire	Copper (Cu)	7440-50-8		0.152	mg	1000000	2815
encapsulation	Other Organic Materials	26.055	mg	supplier	mold compound	Silica, vitreous	60676-86-0		22.848	mg	876914	423111
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		1.043	mg	40031	19315
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		1.043	mg	40031	19315
encapsulation				supplier	mold compound	phenol resin	Proprietary		0.782	mg	30013	14481
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.078	mg	2994	1444
encapsulation				supplier	mold compound	additive	Proprietary		0.261	mg	10017	4833